

Power MOSFET

PRODUCT SUMMARY

V_{DS} (V)	100	
$R_{DS(on)}$ (Ω)	$V_{GS} = 10\text{ V}$	0.54
Q_g (Max.) (nC)	8.3	
Q_{gs} (nC)	2.3	
Q_{gd} (nC)	3.8	
Configuration	Single	

FEATURES

- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- 175 °C Operating Temperature
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Lead (Pb)-free Available

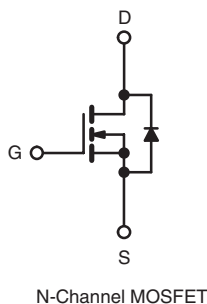
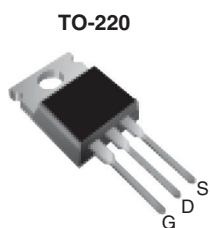


RoHS*
COMPLIANT

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220 contribute to its wide acceptance throughout the industry.



ORDERING INFORMATION

Package	TO-220
Lead (Pb)-free	IRF510PbF SiHF510-E3
SnPb	IRF510 SiHF510

ABSOLUTE MAXIMUM RATINGS $T_C = 25\text{ }^{\circ}\text{C}$, unless otherwise noted

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	5.6	A
$V_{GS} \text{ at } 10\text{ V}$	$T_C = 25\text{ }^{\circ}\text{C}$ $T_C = 100\text{ }^{\circ}\text{C}$	4.0	
Pulsed Drain Current ^a	I_{DM}	20	
Linear Derating Factor		0.29	W/ $^{\circ}\text{C}$
Single Pulse Avalanche Energy ^b	E_{AS}	100	mJ
Repetitive Avalanche Current ^a	I_{AR}	5.6	A
Repetitive Avalanche Energy ^a	E_{AR}	4.3	mJ
Maximum Power Dissipation	P_D	43	W
$T_C = 25\text{ }^{\circ}\text{C}$			
Peak Diode Recovery dV/dt ^c	dV/dt	5.5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 175	$^{\circ}\text{C}$
Soldering Recommendations (Peak Temperature)	for 10 s	300 ^d	
Mounting Torque	6-32 or M3 screw	10 1.1	lbf · in N · m

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 25\text{ V}$, starting $T_J = 25\text{ }^{\circ}\text{C}$, $L = 4.8\text{ mH}$, $R_G = 25\text{ }\Omega$, $I_{AS} = 5.6\text{ A}$ (see fig. 12).
- $I_{SD} \leq 5.6\text{ A}$, $dI/dt \leq 75\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DS}$, $T_J \leq 175\text{ }^{\circ}\text{C}$.
- 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS

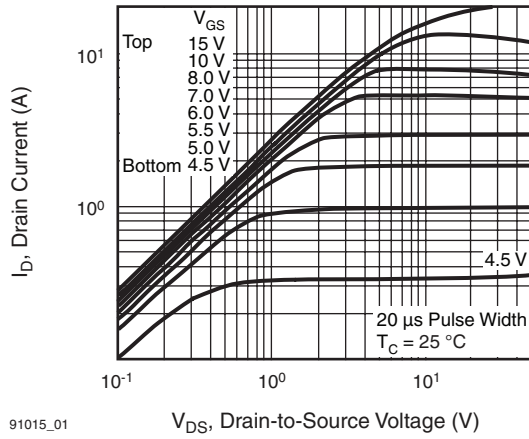
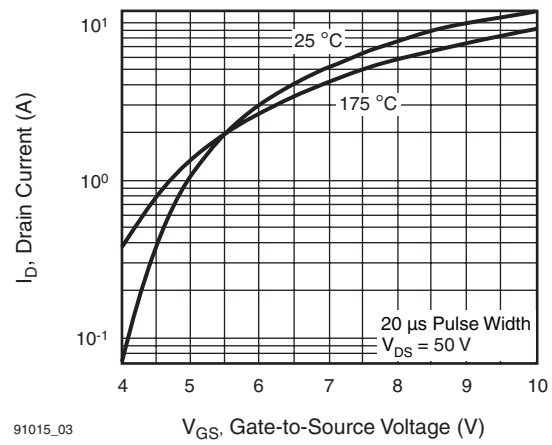
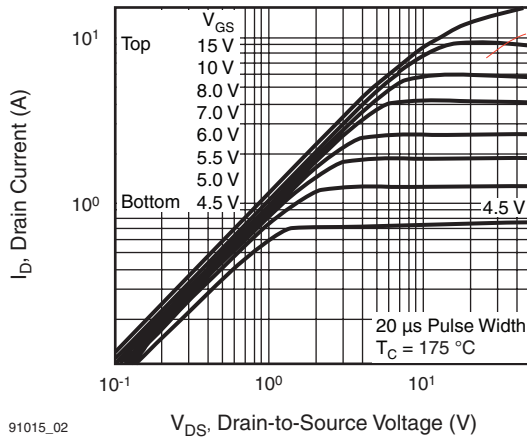
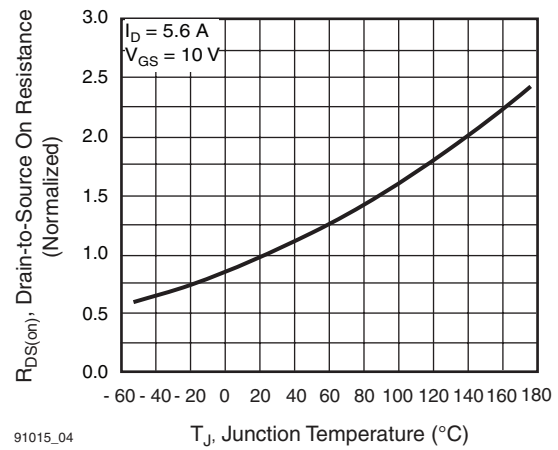
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	62	°C/W
Case-to-Sink, Flat, Greased Surface	R_{thCS}	0.50	-	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	3.5	

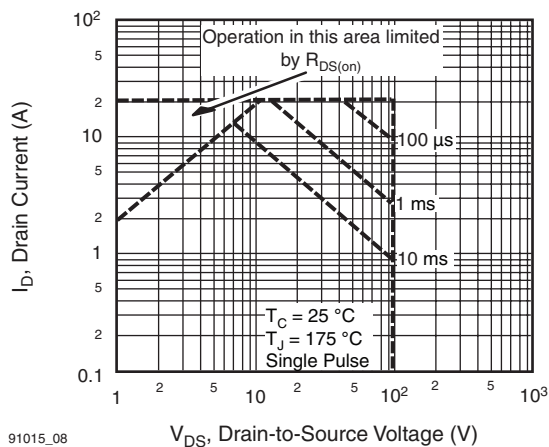
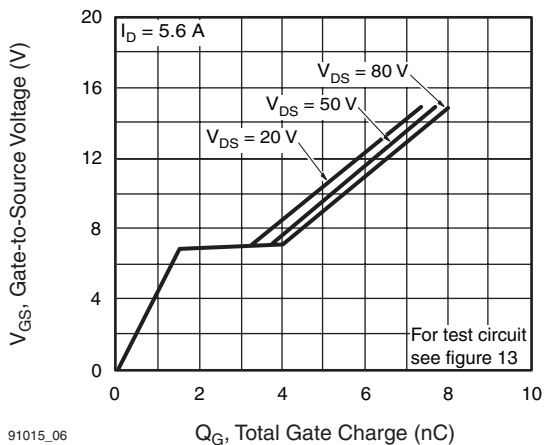
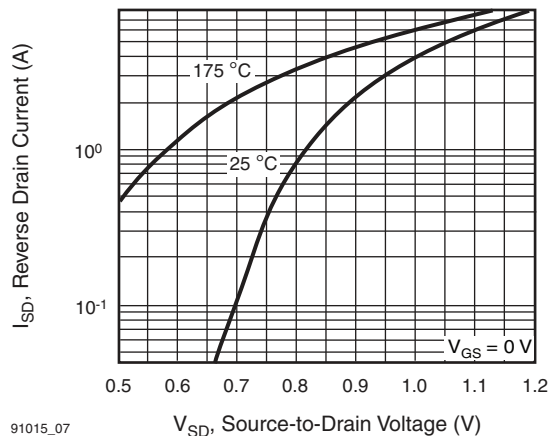
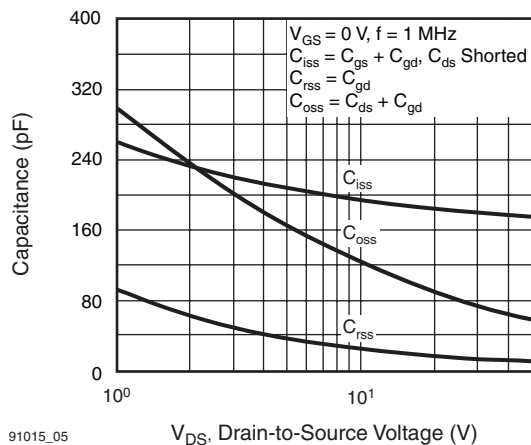
SPECIFICATIONS $T_J = 25\text{ °C}$, unless otherwise noted

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA		100	-	-	V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = 1 mA		-	0.12	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V		-	-	25	μA
		V _{DS} = 80 V, V _{GS} = 0 V, T _J = 150 °C		-	-	250	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D =3.4 A ^b	-	-	0.54	Ω
Forward Transconductance	g _{fs}	V _{DS} = 50 V, I _D = 3.4 A ^b		1.3	-	-	S
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1.0 MHz, see fig. 5		-	180	-	pF
Output Capacitance	C _{oss}			-	81	-	
Reverse Transfer Capacitance	C _{rss}			-	15	-	
Total Gate Charge	Q _g	V _{GS} = 10 V	I _D = 5.6 A, V _{DS} = 80 V	-	-	8.3	nC
Gate-Source Charge	Q _{gs}		V _{DS} = 10 V, see fig. 6 and 13 ^b	-	-	2.3	
Gate-Drain Charge	Q _{gd}		-	-	3.8		
Turn-On Delay Time	t _{d(on)}	V _{DD} = 50 V, I _D = 5.6 A R _G = 24 Ω, R _D = 8.4 Ω, see fig. 10 ^b		-	6.9	-	ns
Rise Time	t _r			-	16	-	
Turn-Off Delay Time	t _{d(off)}			-	15	-	
Fall Time	t _f			-	9.4	-	
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	nH
Internal Source Inductance	L _S			-	7.5	-	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	5.6	A
Pulsed Diode Forward Current ^a	I _{SM}			-	-	20	
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S = 5.6 A, V _{GS} = 0 V ^b		-	-	2.5	V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = 5.6 A, dI/dt = 100 A/μs ^b		-	100	200	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	0.44	0.88	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)					

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

Fig. 1 - Typical Output Characteristics, $T_C = 25^\circ\text{C}$

Fig. 3 - Typical Transfer Characteristics

Fig. 2 - Typical Output Characteristics, $T_C = 175^\circ\text{C}$

Fig. 4 - Normalized On-Resistance vs. Temperature



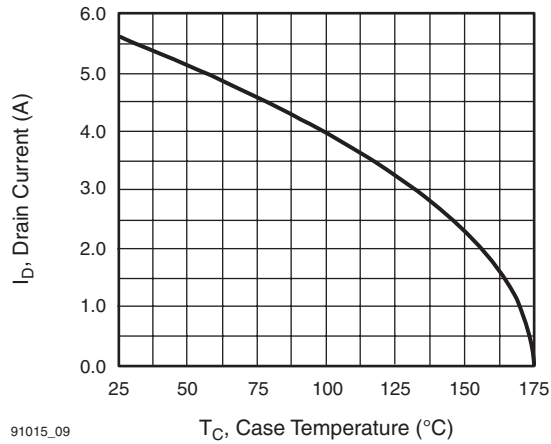


Fig. 9 - Maximum Drain Current vs. Case Temperature

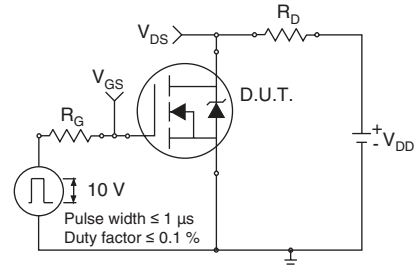


Fig. 10a - Switching Time Test Circuit

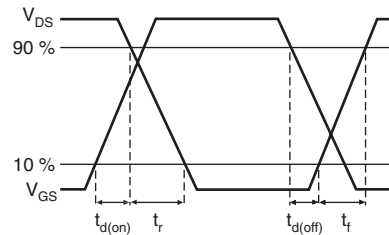


Fig. 10b - Switching Time Waveforms

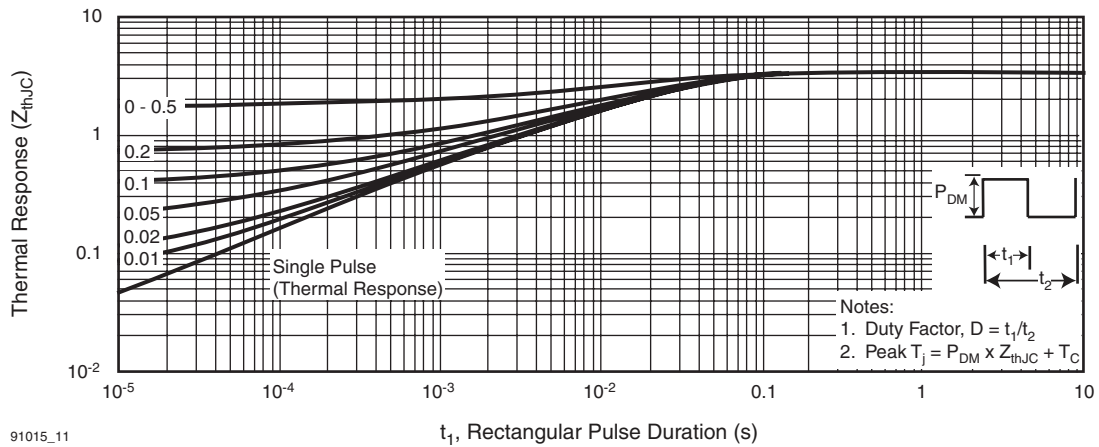


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

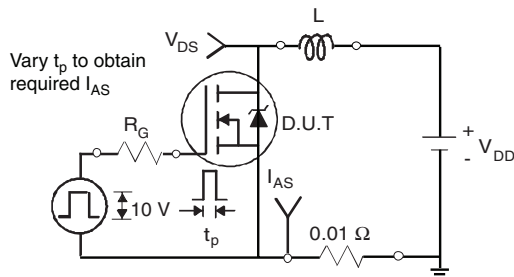


Fig. 12a - Unclamped Inductive Test Circuit

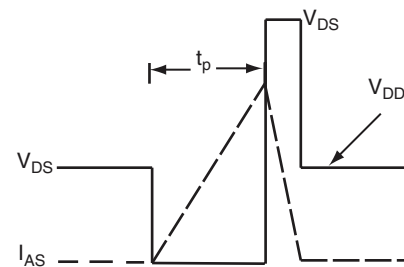


Fig. 12b - Unclamped Inductive Waveforms

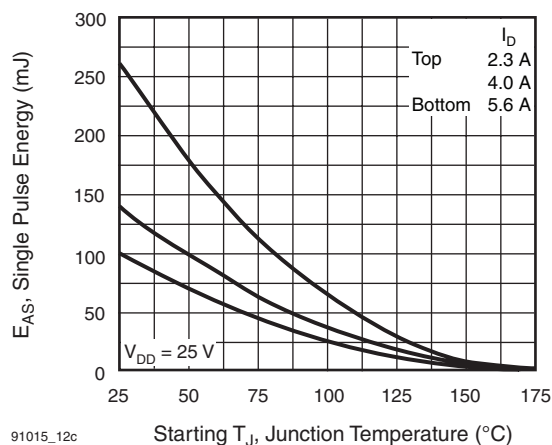


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

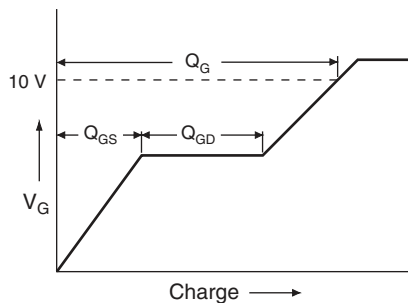


Fig. 13a - Basic Gate Charge Waveform

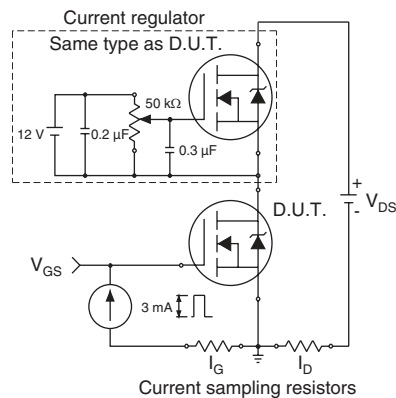


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit

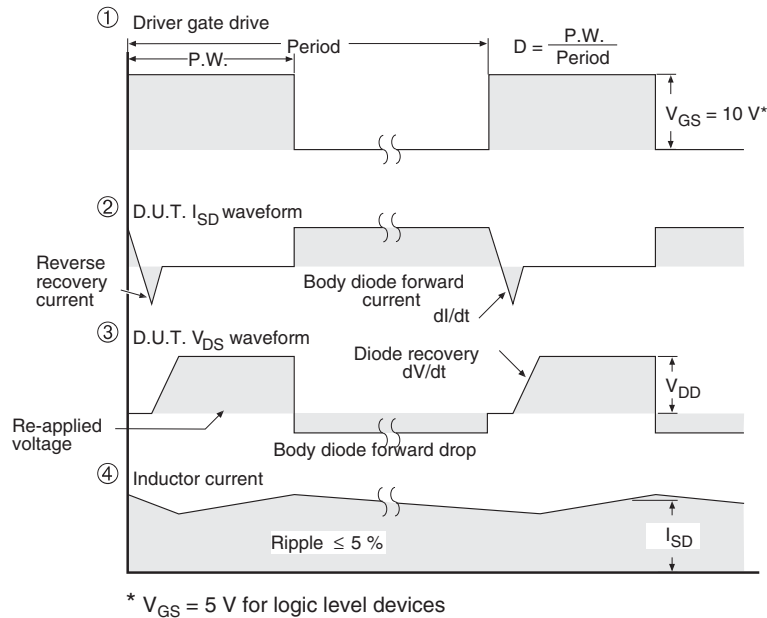
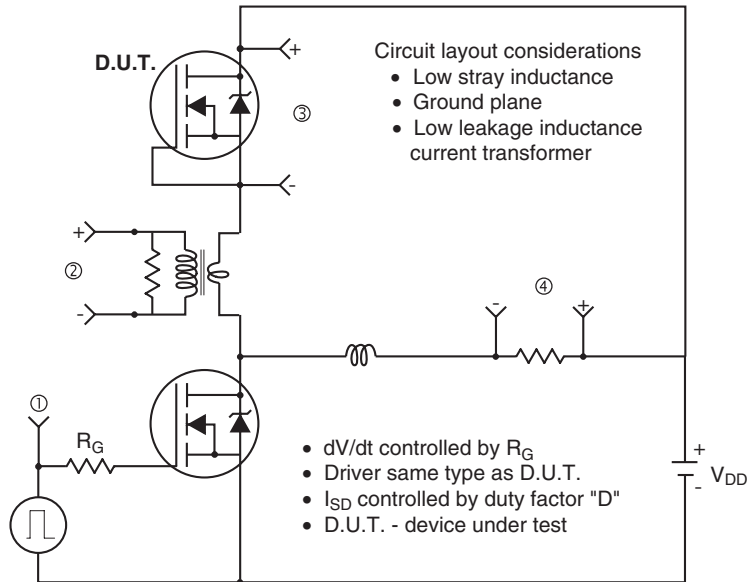


Fig. 14 - For N-Channel

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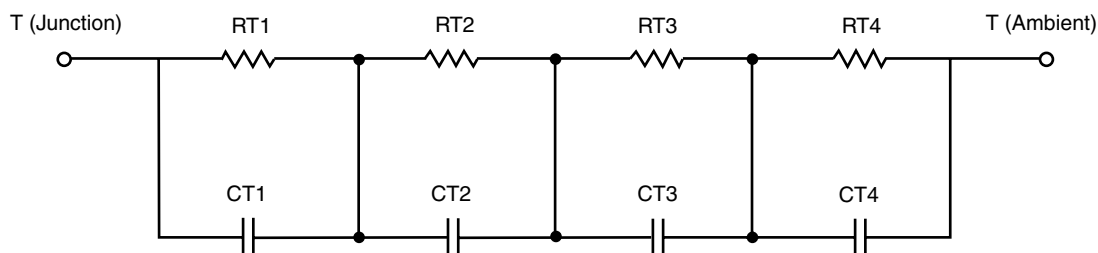
R-C Thermal Model Parameters

DESCRIPTION

The parametric values in the R-C thermal model have been derived using curve-fitting techniques. R-C values for the electrical circuit in the Foster/tank and Cauer/filter configurations are included. When implemented in P-SPICE, these values have matching characteristic curves to the single-pulse transient thermal impedance curves for the MOSFET.

These RC values can be used in the P-SPICE simulation to evaluate the thermal behavior of the MOSFET junction temperature under a defined power profile. These techniques are described in application note AN609, "Thermal Simulation of Power MOSFETs on the P-SPICE Platform".

R-C THERMAL MODEL FOR TANK CONFIGURATION

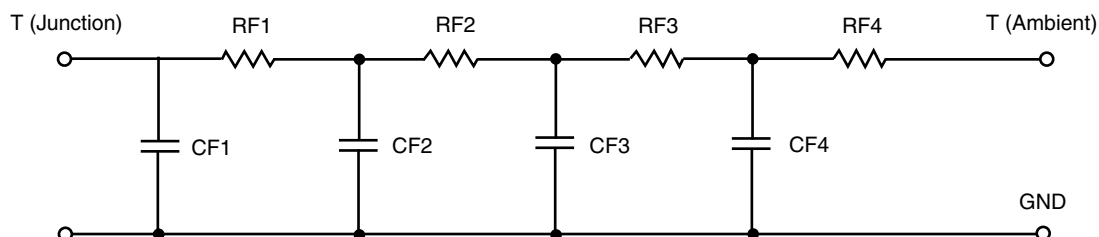


R-C VALUES FOR TANK CONFIGURATION			
THERMAL RESISTANCE (°C/W)			
Junction to	Ambient	Case	Foot
RT1	N/A	917.7500 m	N/A
RT2	N/A	598.2000 m	N/A
RT3	N/A	1.8542	N/A
RT4	N/A	129.9000 m	N/A
THERMAL CAPACITANCE (Joules/°C)			
Junction to	Ambient	Case	Foot
CT1	N/A	118.7943 m	N/A
CT2	N/A	2.1686 m	N/A
CT3	N/A	9.6739 m	N/A
CT4	N/A	251.2953 u	N/A

Note

N/A indicates not applicable

This document is intended as a SPICE modeling guideline and does not constitute a commercial product datasheet. Designers should refer to the appropriate datasheet of the same number for guaranteed specification limits.

R-C THERMAL MODEL FOR FILTER CONFIGURATION**R-C VALUES FOR FILTER CONFIGURATION**

THERMAL RESISTANCE (°C/W)			
Junction to	Ambient	Case	Foot
RF1	N/A	368.9562 m	N/A
RF2	N/A	845.9403 m	N/A
RF3	N/A	1.7024	N/A
RF4	N/A	582.7035 m	N/A
THERMAL CAPACITANCE (Joules/°C)			
Junction to	Ambient	Case	Foot
CF1	N/A	494.4644 u	N/A
CF2	N/A	2.4212 m	N/A
CF3	N/A	8.3073 m	N/A
CF4	N/A	165.3498 m	N/A

Note

N/A indicates not applicable

